

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Wei-Che HSIEH</td> <td>12/14/2012</td> </tr> <tr> <td>Brian WANG</td> <td>12/14/2012</td> </tr> <tr> <td>Tze-Liang LEE</td> <td>12/14/2012</td> </tr> <tr> <td>Yi-Hung LIN</td> <td>12/14/2012</td> </tr> <tr> <td>Hao-Ming LIEN</td> <td>12/14/2012</td> </tr> <tr> <td>Shiang-Rung TSAI</td> <td>12/14/2012</td> </tr> <tr> <td>Tai-Chun HUANG</td> <td>12/14/2012</td> </tr> </tbody> </table>		Name	Execution Date	Wei-Che HSIEH	12/14/2012	Brian WANG	12/14/2012	Tze-Liang LEE	12/14/2012	Yi-Hung LIN	12/14/2012	Hao-Ming LIEN	12/14/2012	Shiang-Rung TSAI	12/14/2012	Tai-Chun HUANG	12/14/2012
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<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. VI</td> </tr> <tr> <td>Internal Address:</td> <td>Hsinchu Science Park</td> </tr> <tr> <td>City:</td> <td>Hsinchu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-78</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	Street Address:	No. 8, Li-Hsin Rd. VI	Internal Address:	Hsinchu Science Park	City:	Hsinchu	State/Country:	TAIWAN	Postal Code:	300-78				
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CORRESPONDENCE DATA																	
Fax Number:	9498519348																
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>																	
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CH \$40.00 13716052

ATTORNEY DOCKET NUMBER:	091393-0024
NAME OF SUBMITTER:	John D. Magluyan, Reg. No. 56,867
Total Attachments: 1 source=091393-0024_Assignment#page1.tif	

台積電編號: TSMC2012-0534; 本所編號: PECA 18632/5755

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned,

(1) Wei-Che Hsieh, Brian Wang, Tze-Liang Lee, Yi-Hung Lin, Hao-Ming Lien, Shiang-Rung Tsai, Tai-Chun Huang

HEREBY SELL(S), ASSIGN(S) AND TRANSFER(S) TO

(2) Taiwan Semiconductor Manufacturing Company, Ltd having a place of business at

(3) No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

(hereinafter called "ASSIGNEE") the entire right, title and interest in and to any and all improvements which are disclosed in the application for United States Letters Patent entitled

(4) INJECTOR FOR FORMING FILMS RESPECTIVELY ON A STACK OF WAFERS
which application was:

(a) executed by the undersigned on (5a) December 14, 2012

(b) filed on (5b) _____

And assigned Serial No. _____

including any and all United States letters Patents which may be granted on said application, and any and all extensions, divisions, reissues, substitutes, renewals or continuations of said application and patents, and the right to all benefits under all international conventions for the protection of industrial property and applications for said improvements.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said Assignee, its assigns or its successors in interest or its designee.

Upon said consideration, it is further agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, renewal, and reissue patent applications; execute all rightful other papers; and generally do everything possible which said Assignee shall consider desirable for aiding in securing and maintaining patent protection as provided herein.

DATE:

INVENTOR(S)

December 14, 2012

Wei-Che Hsieh

Wei-Che Hsieh

December 14, 2012

Brian Wang

Brian Wang

December 14, 2012

Tze-Liang Lee

Tze-Liang Lee

December 14, 2012

Yi-Hung Lin

Yi-Hung Lin

December 14, 2012

Hao-Ming Lien

Hao-Ming Lien

December 14, 2012

Shiang-Rung Tsai

Shiang-Rung Tsai

December 14, 2012

Tai-Chun Huang

Tai-Chun Huang

PATENT

RECORDED: 12/19/2012

REEL: 029505 FRAME: 0705